



Recommended P.C.B. Layout
Layout Tolerance = ± 0.05 mm

NOTE:

1. MATERIAL,
HOUSING: HIGH TEMP PLASTIC, UL94-V0, BLACK
TERMINAL: COPPER ALLOY, SQ=0.40±0.03MM
2. FINISH:
TERMINAL: GOLD AT CONTACT,
G/F OVER 1um(40u") MIN Ni OVER ALL
3. SPEC.:
PRODUCT SPEC: GS-12-629
PACKING SPEC: GS-14-1420
4. THE HSG. WILL WITHSTAND EXPOSURE TO 260C
PEAK TEMP. FOR 5 SEC. IN A WAVE SOLDER APPLICATION
WITH A PCB.
5. PRODUCT NUMBERING:
20021612 - 0 0 0 XX X X LF

LEAD FREE

PLATING:

1:GOLD FLASH ALL OVER

4:0.25um(10U")GOLD AT CONTACT

8:0.76um(30U")GOLD AT CONTACT

9:1u" GOLD OVER 30u" PdNi AT CONTACT

PACKING

T: TUBE

PIN COUNT
SEE TABLE 1

TABLE 1

DASH No.	Dim.	Amount of Pins	Dim.A	Dim.B	Dim.C
-000 06 XX LF	6	2.54	18.31	8.46	
-000 10 XX LF	10	5.08	20.85	11.00	
-000 12 XX LF	12	6.35	22.12	12.27	
-000 14 XX LF	14	7.62	23.39	13.54	
-000 16 XX LF	16	8.89	24.66	14.81	
-000 20 XX LF	20	11.43	27.20	17.35	
-000 26 XX LF	26	15.24	31.01	21.16	
-000 30 XX LF	30	17.78	33.55	23.70	
-000 34 XX LF	34	20.32	36.09	26.24	
-000 40 XX LF	40	24.13	39.90	30.05	
-000 44 XX LF	44	26.67	42.44	32.59	
-000 50 XX LF	50	30.48	46.25	36.40	
-000 60 XX LF	60	36.83	52.60	42.75	
-000 64 XX LF	64	39.37	55.14	45.29	
-000 66 XX LF	66	40.64	56.41	46.56	
-000 68 XX LF	68	41.91	57.68	47.83	

mat'l. code		surface	tolerance	projection	product family
		ISO1302	ISO1101 ISO406		MINITEK
l tr ecn nodr		date	tolerances unless otherwise specified		
A	T09-1117	S.LIN	09/15/09	MM	1.27X1.27MM BTB EHECT HEADER
B	T10-0026	S.LIN	01/20/10		RIGHT ANGLE TH
C	EX-N-010366	ZK	01/16/12	scale 2:1	
		dr	STERLING LIN	09/15/09	dwg no
		engr	STERLING LIN	09/15/09	sheet 1 of 1
		chr	GRAY HSIEH	09/15/09	size
		appd	JOSEPH	09/15/09	A4
sheet	revision	inc			type
index	sheet	1			Product Customer Drawing